Product data sheet

1. General description

Planar passivated AC Thyristor Triac power switch in a SOT186A (TO-220F) "full pack" plastic package with self-protective capabilities against low and high energy transients. This "series COT" triac will commutate the full RMS current at the maximum rated junction temperature ($T_{j(max)}$ = 150 °C) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

2. Features and benefits

- · Clamping structure ensuring safe high over-voltage withstand capability
- · High junction operating temperature capability
- High minimum I_{GT} for guaranteed immunity to gate noise
- Full cycle AC conduction
- Isolated mounting base package
- Less sensitive gate for high noise immunity
- Over-voltage withstand capability to IEC 61000-4-5
- · Pin compatible with standard triacs
- Planar passivated for voltage ruggedness and reliability
- Safe clamping capability for low energy over-voltage transients
- · Self-protective turn-on during high energy voltage transients
- · Triggering in three quadrants only
- Very high immunity to false turn-on by dV/dt

3. Applications

- AC fan, pump and compressor controls
- Highly inductive, resistive and safety loads
- Large and small appliances (White Goods)
- · Reversing induction motor controls
- · Applications subject to high temperature

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DRM}	repetitive peak off- state voltage		-	-	800	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_h \le 104$ °C; Fig. 1; Fig. 2; Fig. 3	-	-	8	Α
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)} = 25 ^{\circ}\text{C}$; $t_p = 20 \text{ms}$; Fig. 4; Fig. 5	-	-	80	Α

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
		full sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 16.7 \text{ ms}$	-	-	88	Α
Tj	junction temperature		-	-	150	°C
V_{PP}	peak pulse voltage	T _j = 25 °C; non-repetitive, off-state; Fig. 6	-	-	2	kV
Static chara	acteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 100 \text{ mA; LD+ G+;}$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 8}}{\text{C}}$	5	-	30	mA
		$V_D = 12 \text{ V; } I_T = 100 \text{ mA; LD+ G-;}$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 8}}{\text{C}}$	5	-	30	mA
		$V_D = 12 \text{ V; } I_T = 100 \text{ mA; LD- G-;}$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 8}}{\text{C}}$	5	-	30	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 10</u>	-	-	35	mA
V _T	on-state voltage	I _T = 10 A; T _j = 25 °C; <u>Fig. 11</u>	-	1.3	1.5	V
V _{CL}	clamping voltage	I_{CL} = 0.1 mA; t_p = 1 ms; T_j = 25 °C	850	-	-	V
Dynamic ch	naracteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 536 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	600	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	$V_D = 400 \text{ V}$; $T_j = 150 \text{ °C}$; $I_{T(RMS)} = 8 \text{ A}$; $dV_{com}/dt = 20 \text{ V/}\mu\text{s}$; (snubberless condition); gate open circuit	3	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	СМ	common	mb	LD L
2	LD	load		
3	G	gate		G—
mb	n.c.	mounting base; isolated	1 2 3 TO-220F (SOT186A)	CM 003aaf296

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
ACTT8X-800C0T	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A

7. Limiting values

Table 4. Limiting values
In accordance with the Absolute Maximum Rating System (IFC 60134)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	800	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_h \le 104$ °C; $Fig. 1$; $Fig. 2$; $Fig. 3$	-	8	Α
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig. 4; Fig. 5	-	80	Α
		full sine wave; $T_{j(init)}$ = 25 °C; t_p = 16.7 ms	-	88	Α
l ² t	I ² t for fusing	t _p = 10 ms; sine-wave pulse	-	32	A²s
dl _T /dt	rate of rise of on-state current	I _G = 0.2 A	-	100	A/µs
I _{GM}	peak gate current	t = 20 μs	-	2	Α
P_{GM}	peak gate power		-	5	W
P _{G(AV)}	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-	150	°C
V_{PP}	peak pulse voltage	T _i = 25 °C; non-repetitive, off-state; Fig. 6	-	2	kV

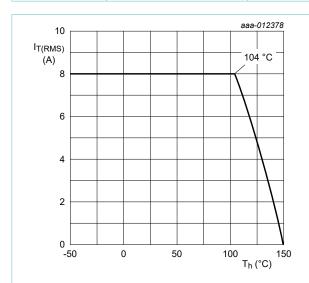


Fig. 1. RMS on-state current as a function of heatsink temperature; maximum values

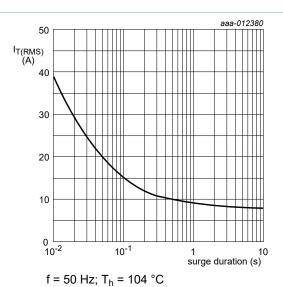


Fig. 2. RMS on-state current as a function of surge duration; maximum values

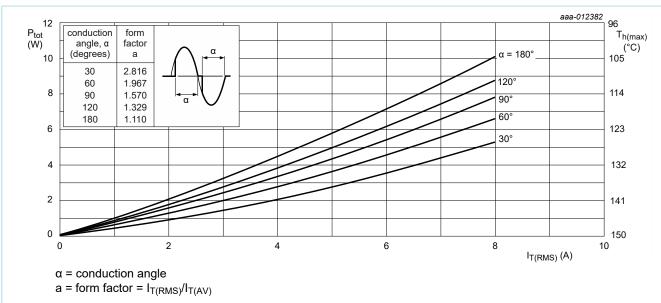


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

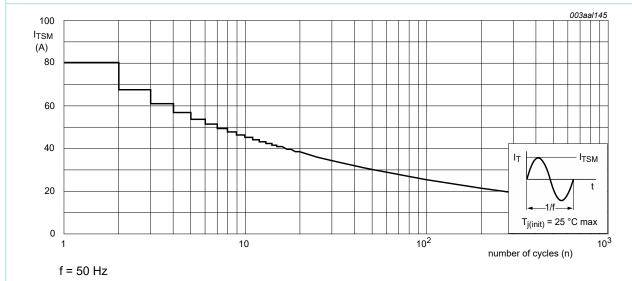


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

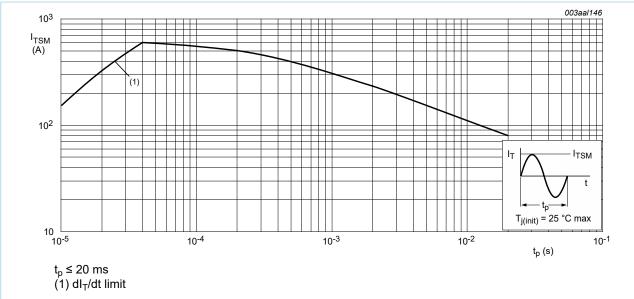


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

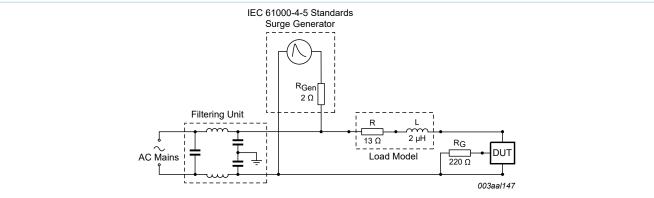
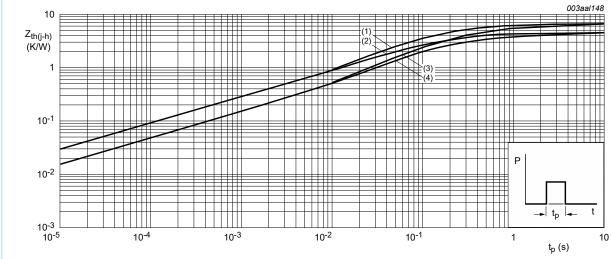


Fig. 6. Test circuit for inductive and resistive loads with conditions equivalent to IEC 61000-4-5

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-h)}	thermal resistance from junction to	full or half cycle with heatsink compound; Fig. 7	-	-	4.5	K/W
	heatsink	full or half cycle without heatsink compound; Fig. 7	-	-	6.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W



- (1) Unidirectional (half cycle) without heatsink compound
- (2) Unidirectional (half cycle) with heatsink compound
- (3) Bidirectional (full cycle) without heatsink compound
- (4) Bidirectional (full cycle) with heatsink compound

Fig. 7. Transient thermal impedance from junction to heatsink as a function of pulse width

9. Isolation characteristics

Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	sinusoidal waveform; from all pins to external heatsink; clean and dust free; $50 \text{ Hz} \le f \le 60 \text{ Hz}$; $RH \le 65 \%$; $T_h = 25 \text{ °C}$	-	-	2500	V
C _{isol}	isolation capacitance	from LD pin to external heatsink; f = 1 MHz; T _h = 25 °C	-	10	-	pF

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static char	acteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; LD+ G+;$ $T_j = 25 \text{ °C}; Fig. 8$	5	-	30	mA
		$V_D = 12 \text{ V; } I_T = 100 \text{ mA; LD+ G-;}$ $T_j = 25 \text{ °C; Fig. 8}$	5	-	30	mA
		$V_D = 12 \text{ V; } I_T = 100 \text{ mA; LD- G-;}$ $T_j = 25 \text{ °C; Fig. 8}$	5	-	30	mA
lL	latching current	$V_D = 12 \text{ V; } I_G = 100 \text{ mA; LD+ G+;}$ $T_j = 25 \text{ °C; Fig. 9}$	-	-	50	mA
		$V_D = 12 \text{ V; } I_G = 100 \text{ mA; LD+ G-;}$ $T_j = 25 \text{ °C; Fig. 9}$	-	-	70	mA
		$V_D = 12 \text{ V; } I_G = 100 \text{ mA; LD- G-;}$ $T_j = 25 \text{ °C; Fig. 9}$	-	-	50	mA
lн	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 10</u>	-	-	35	mA
V _T	on-state voltage	I _T = 10 A; T _j = 25 °C; <u>Fig. 11</u>	-	1.3	1.5	V
V_{GT}	gate trigger voltage	V _D = 12 V; I _T = 100 mA; T _j = 25 °C; Fig. 12	-	0.8	1	V
		V _D = 400 V; I _T = 100 mA; T _j = 150 °C; Fig. 12	0.2	0.45	-	V
l _D	off-state current	V _D = 800 V; T _j = 25 °C	-	-	10	μΑ
		V _D = 800 V; T _j = 150 °C	-	-	2	mA
V _{CL}	clamping voltage	$I_{CL} = 0.1 \text{ mA}; t_p = 1 \text{ ms}; T_j = 25 \text{ °C}$	850	-	-	V
Dynamic cl	naracteristics			'	'	
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 536 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	600	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 150 \text{ °C}; I_{T(RMS)} = 8 \text{ A};$ $dV_{com}/dt = 20 \text{ V/}\mu\text{s}; \text{ (snubberless condition)}; \text{ gate open circuit}$	3	-	-	A/ms

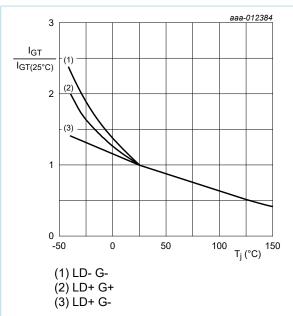


Fig. 8. Normalized gate trigger current as a function of junction temperature

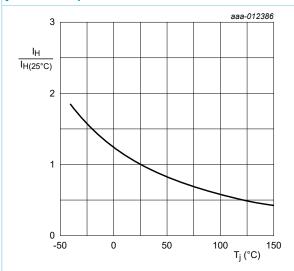


Fig. 10. Normalized holding current as a function of junction temperature

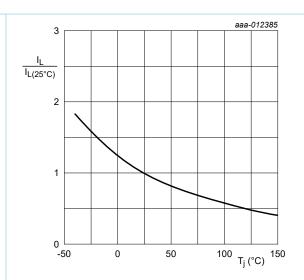
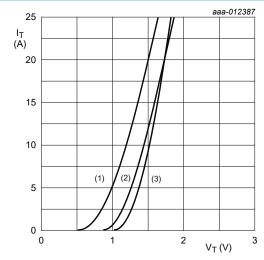


Fig. 9. Normalized latching current as a function of junction temperature



 V_o = 1.103 V; R_s = 0.034 Ω

(1) $T_j = 150$ °C; typical values (2) $T_j = 150$ °C; maximum values (3) $T_j = 25$ °C; maximum values

Fig. 11. On-state current as a function of on-state voltage

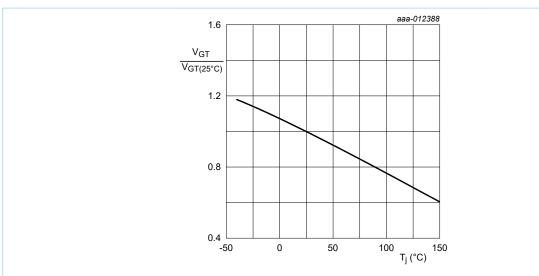
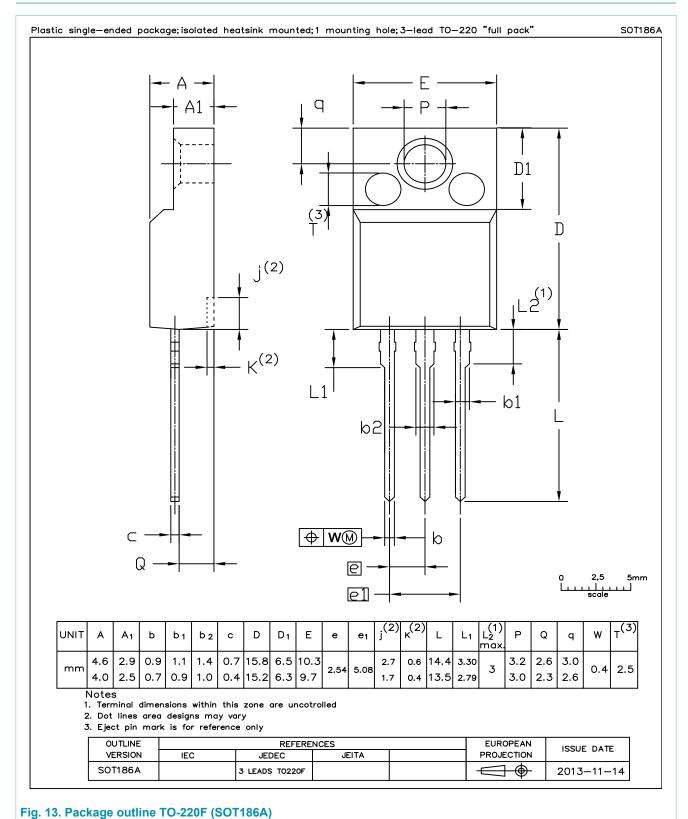


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

11. Package outline



12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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